

低噪声 JFET 输入运算放大器

查询样品: [TL072-EP](#), [TL074-EP](#)

特性

- 低功耗
- 宽共模和差分电压范围
- 低输入偏压和偏移电流
- 输出短路保护
- 低总谐波失真: 典型值 **0.003%**
- 低噪声, $f=1\text{kHz}$ 时, 典型值为 $V_n=18\text{nV}/\sqrt{\text{Hz}}$
- 高输入阻抗: JFET 输入级
- 内部频率补偿
- 无锁存运行
- 高转换率: 典型值为 **13 V/ μs**
- 共模输入电压范围包括 V_{CC+}

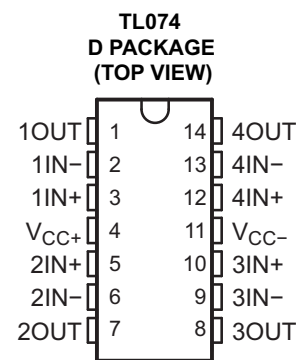
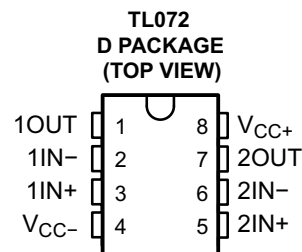
支持国防、航空航天、和医疗应用

- 受控基线
- 一个组装和测试场所
- 一个制造场所
- 扩展温度范围 (**-40°C 至 125°C**) 或军用 (**-55°C 至 125°C**) 温度范围内可用
- 延长的产品生命周期
- 拓展的产品变更通知
- 产品可追溯性

说明/订购信息

在 TL07x 中的 JFET-输入运算放大器与 TL08x 系列产品类似, 具有低输入偏压和偏移电流以及快速转换率。TL07x 的低谐波失真和低噪音使得它非常适合高保真和音频前置功放应用。每个放大器特有 JFET 输入 (用于高输入阻抗), 此输入与集成在一个单片芯片上的双极输出级耦合在一起。

TL07x 可在扩展温度范围 (-40°C 至 125°C) 或军用温度范围 (-55°C 至 125°C) 内运行。



ORDERING INFORMATION⁽¹⁾

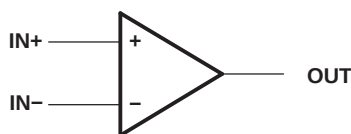
T _A	V _{IO} max AT 25°C	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING	VID NUMBER
-40°C to 125°C	6 mV	SOIC – D	Reel of 2500	TL072QDREP	TL072Q	V62/12604-01XE
				TL074QDREP	TL074Q	V62/11621-01XE
-55°C to 125°C	6 mV	SOIC – D	Reel of 2500	TL074MDREP	TL074M	V62/11621-02XE
			Tube of 75	TL074MDEP	TL074M	V62/11621-02XE-T

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

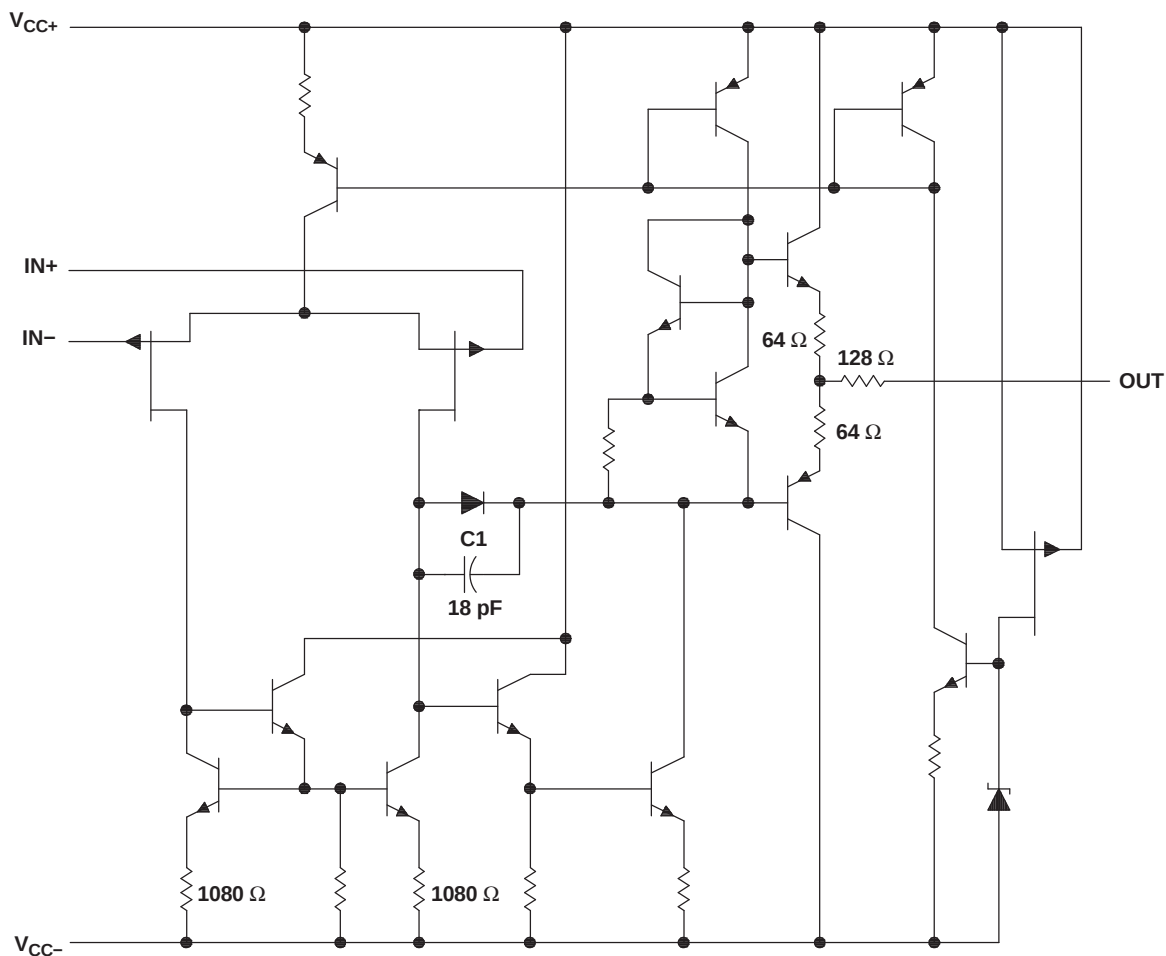


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TL072 and TL074 SYMBOL (EACH AMPLIFIER)



SCHEMATIC (EACH AMPLIFIER)



All component values shown are nominal.

COMPONENT COUNT ⁽¹⁾		
COMPONENT TYPE	TL072	TL074
Resistors	22	44
Transistors	28	56
JFET	4	6
Diodes	2	4
Capacitors	2	4
epi-FET	2	4

(1) Includes bias and trim circuitry

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC+}	Supply voltage ⁽²⁾			18	V
V _{CC-}				18	
V _{ID}	Differential input voltage ⁽³⁾			±30	V
V _I	Input voltage ^{(2) (4)}			±15	V
	Duration of output short circuit ⁽⁵⁾			Unlimited	
θ_{JA}	Thermal resistance, junction-to-ambient ^{(6) (7)}	TL072		97.5	°C/W
		TL074		86	
θ_{JC}	Thermal resistance, junction-to-case ⁽⁷⁾	TL072		38.3	°C/W
		TL074		51.5	
T _J	Operating virtual junction temperature			150	°C
T _{stg}	Storage temperature range			–65 150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
- (3) Differential voltages are at IN+, with respect to IN–.
- (4) The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
- (5) The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- (6) Operating at the absolute maximum T_J of 150°C can affect reliability.
- (7) The package thermal impedance is calculated in accordance with JESD 51-7.

ELECTRICAL CHARACTERISTICS

 $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS ⁽¹⁾	T _A ⁽²⁾	TL072		TL074		UNIT
				MIN	TYP	MAX	MIN	
V _{IO}	Input offset voltage	V _O = 0, R _S = 50 Ω	25°C	3 6		3 6		mV
			Full range	8		8		
α _{VIO}	Temperature coefficient of input offset voltage	V _O = 0, R _S = 50 Ω	Full range	18		18		μV/°C
I _{IO}	Input offset current	V _O = 0	25°C	5	100	5	100	pA
			125°C	2		2		nA
I _{IB}	Input bias current	V _O = 0	25°C	65	200	65	200	pA
			125°C	20		20		nA
V _{ICR}	Common-mode input voltage range		25°C	±11	–12 to 15	±11	–12 to 15	V
V _{OM}	Maximum peak output voltage swing	R _L = 10 kΩ	25°C	±12	±13.5	±12	±13.5	V
		R _L ≥ 10 kΩ	Full range	±12		±12		
		R _L ≥ 2 kΩ		±10		±10		
A _{VD}	Large-signal differential voltage amplification	V _O = ±10 V, R _L ≥ 2 kΩ	25°C	35	200	35	200	V/mV
			Full range	15		15		
B ₁	Unity-gain bandwidth		25°C	3		3		MHz
r _i	Input resistance		25°C	10 ¹²		10 ¹²		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICRmin} , V _O = 0, R _S = 50 Ω	25°C	80	86	80	86	dB
k _{SVR}	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	V _{CC} = ±9 V to ±15 V, V _O = 0, R _S = 50 Ω	25°C	80	86	80	86	dB
I _{CC}	Supply current (each amplifier)	V _O = 0, No load	25°C	1.4	2.5	1.4	2.5	mA
V _{O1} /V _{O2}	Crosstalk attenuation	A _{VD} = 100	25°C	120		120		dB

- Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 3. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.
- All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is $T_A = -40^\circ\text{C}$ to 125°C for TL072xQ and $T_A = -55^\circ\text{C}$ to 125°C for TL074xM.

OPERATING CHARACTERISTICS

 $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS		TL072			TL074			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain	$V_I = 10\text{ V}$, $C_L = 100\ \text{pF}$, $R_L = 2\ \text{k}\Omega$, See Figure 1	8	13		8	13		V/ μs
t_r	Rise-time overshoot factor	$V_I = 20\text{ V}$, $C_L = 100\ \text{pF}$, $R_L = 2\ \text{k}\Omega$, See Figure 1		0.1			0.1		μs
				20			20		%
V_n	Equivalent input noise voltage	$R_S = 20\ \Omega$		18			18		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ Hz}$ to 10 kHz		4			4		μV
I_n	Equivalent input noise current	$R_S = 20\ \Omega$, $f = 1\text{ kHz}$		0.01			0.01		$\text{pA}/\sqrt{\text{Hz}}$
THD	Total harmonic distortion	$V_{I\text{rms}} = 6\text{ V}$, $R_L \geq 2\ \text{k}\Omega$, $f = 1\text{ kHz}$, $A_{VD} = 1$, $R_S \leq 1\ \text{k}\Omega$		0.003			0.003		%

PARAMETER MEASUREMENT INFORMATION

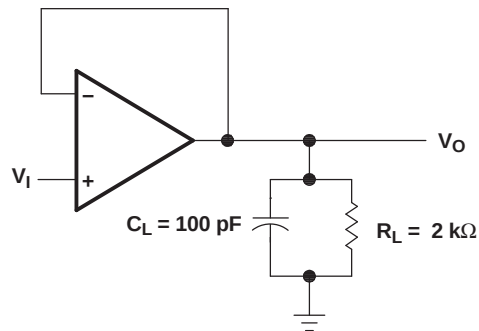


Figure 1. Unity-Gain Amplifier

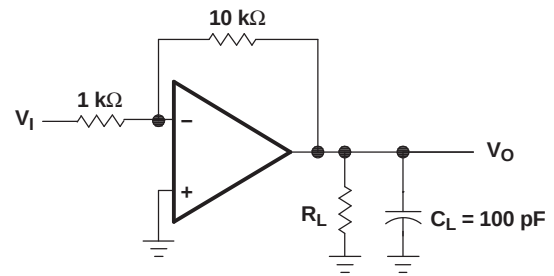


Figure 2. Gain-of-10 Inverting Amplifier

TYPICAL CHARACTERISTICS

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

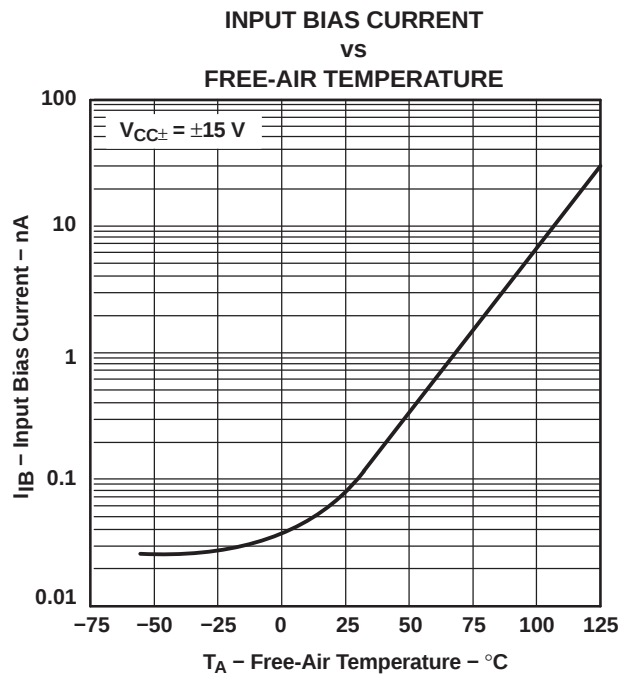


Figure 3.

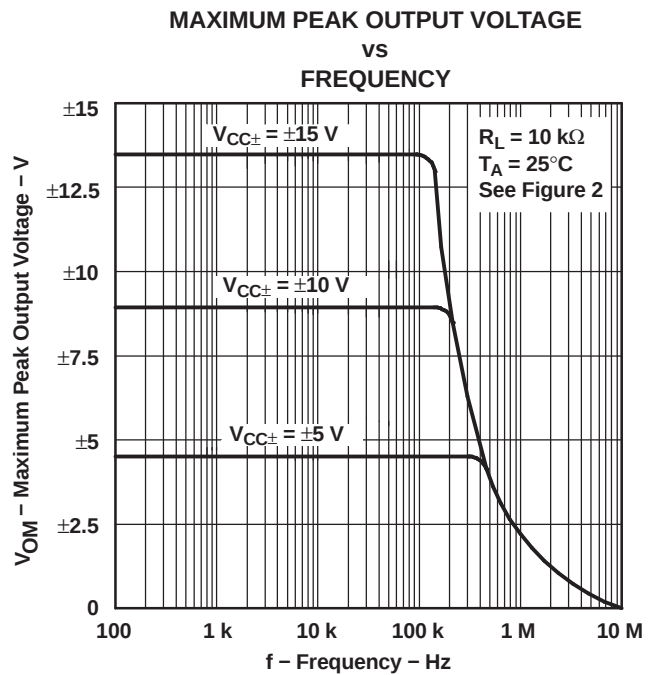


Figure 4.

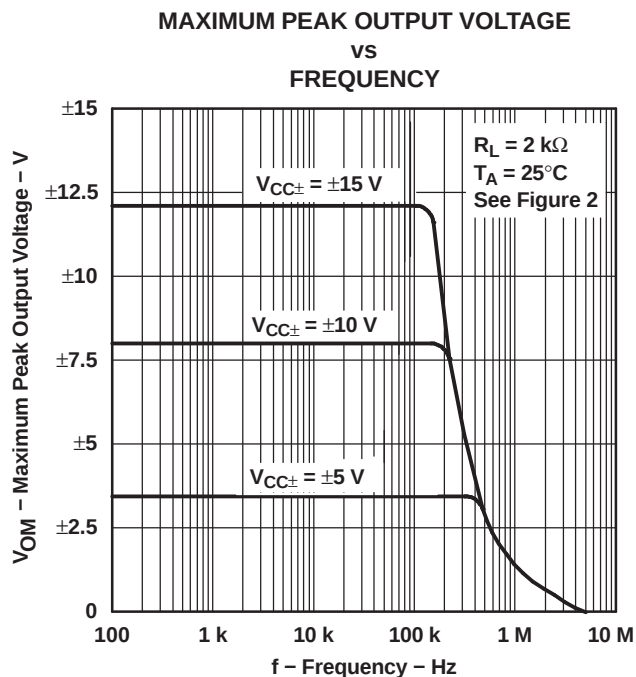


Figure 5.

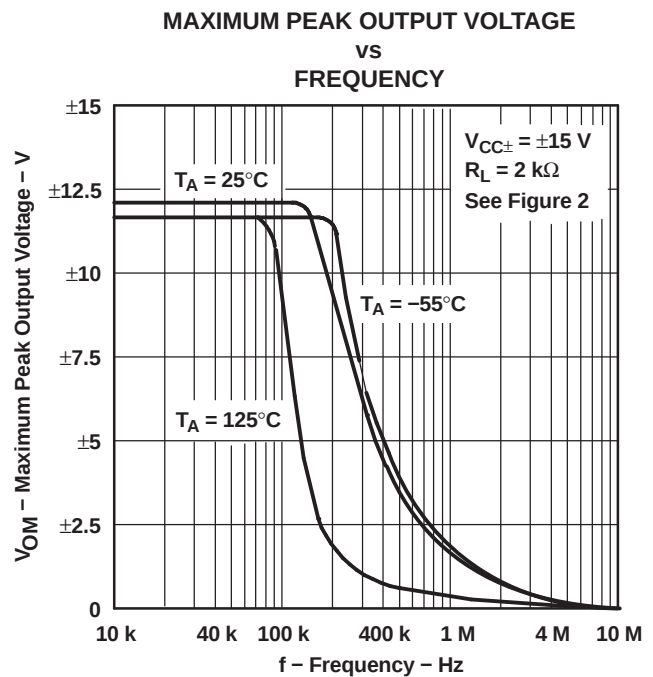


Figure 6.

TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

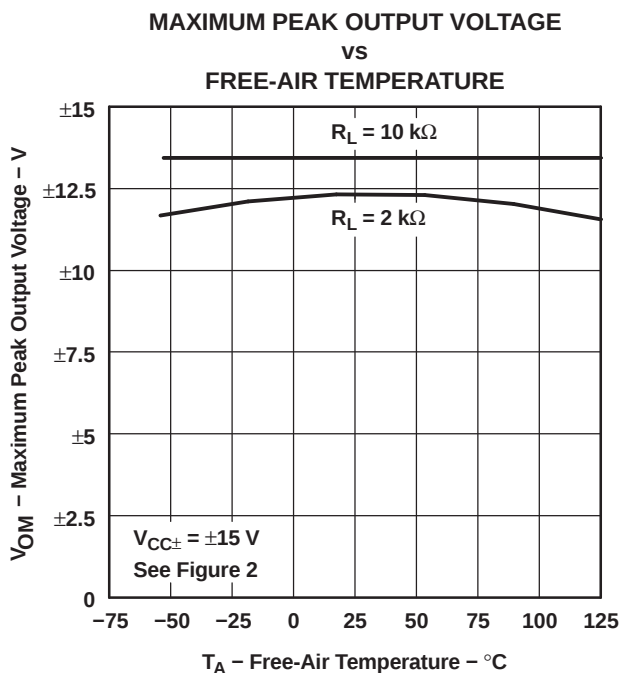


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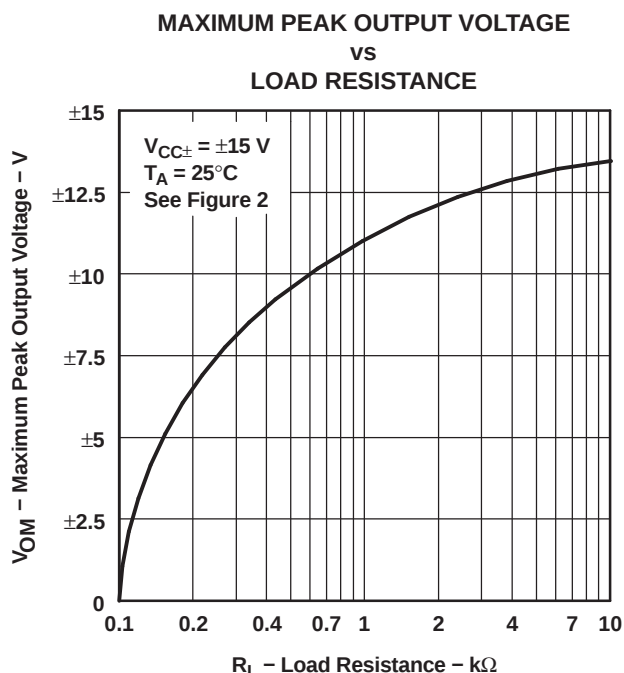


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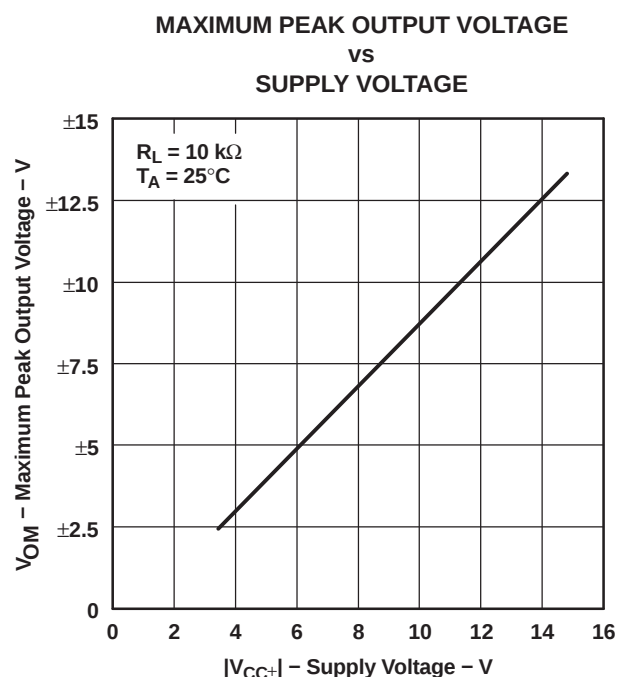


Figure 9.

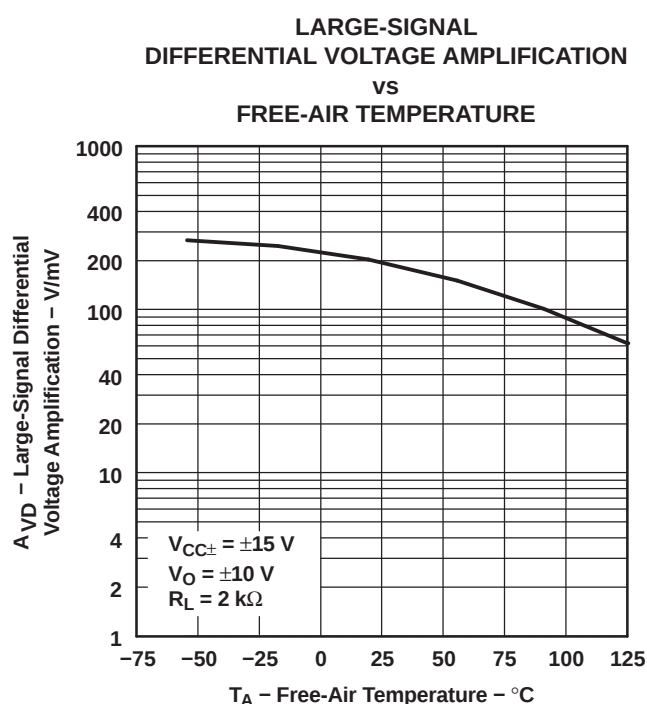


Figure 10.

TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

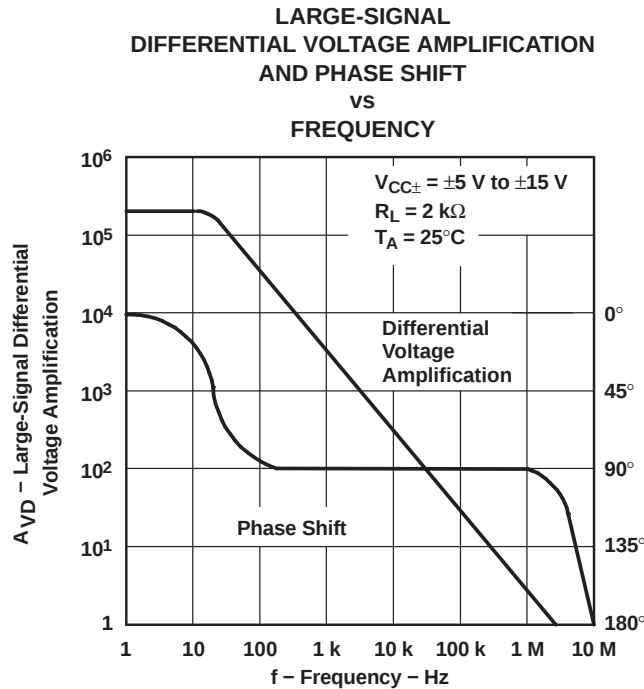


Figure 11.

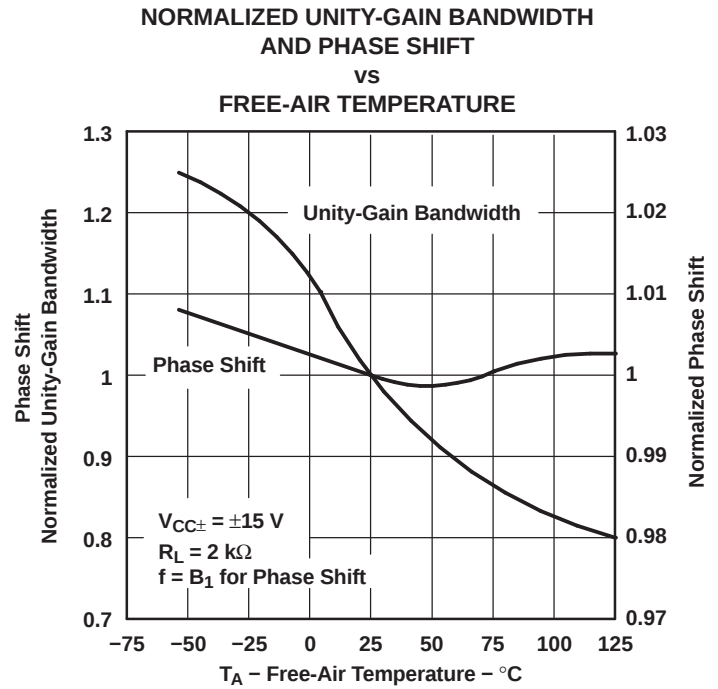


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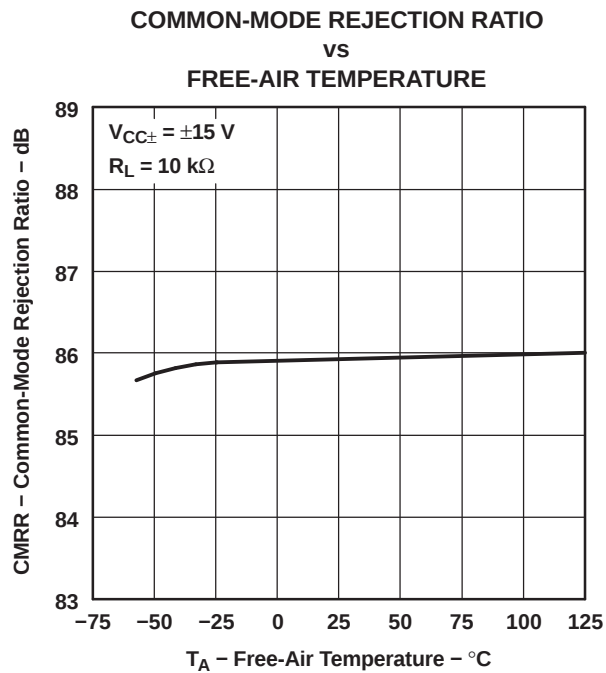


Figure 13.

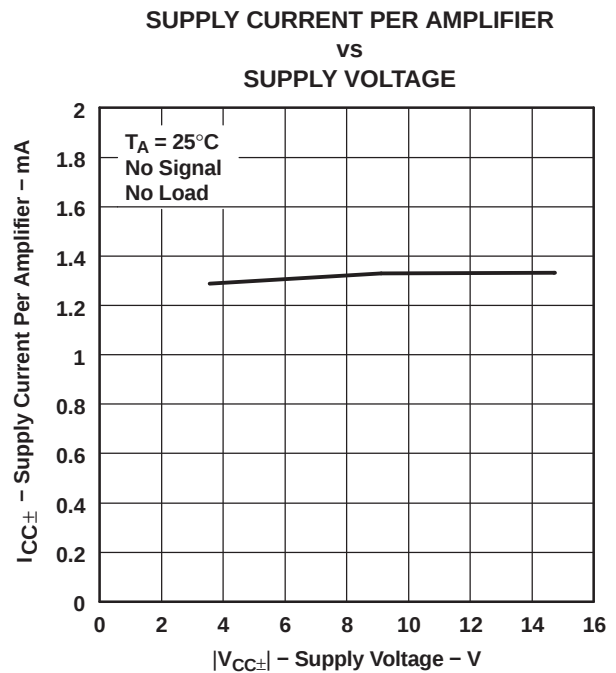


Figure 14.

TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

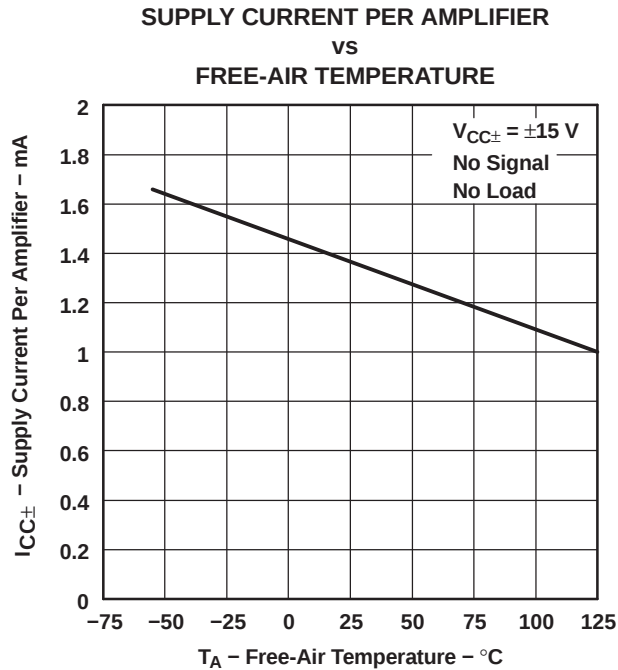


Figure 15.

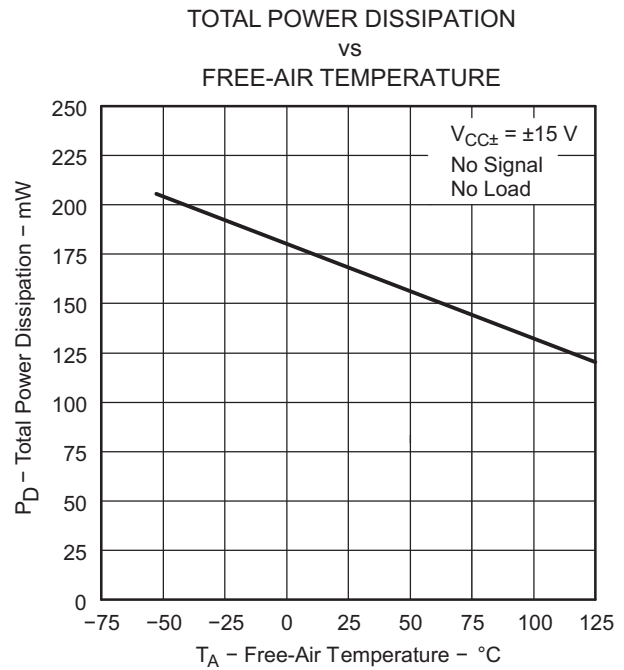


Figure 16.

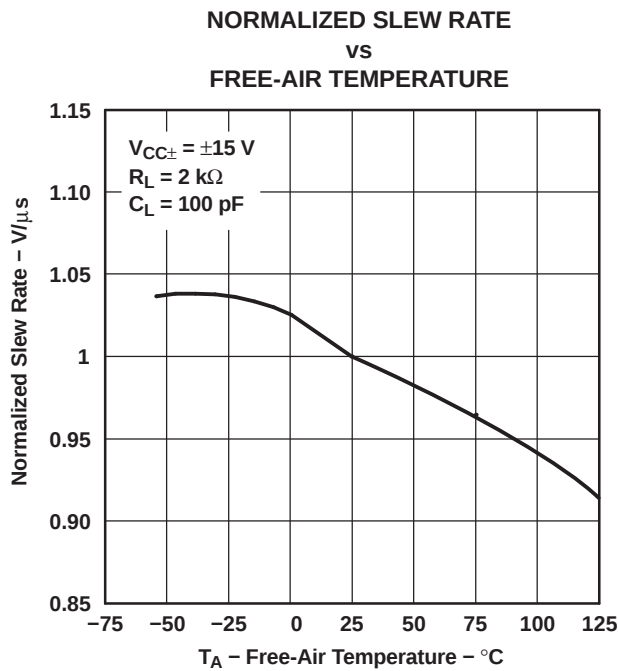


Figure 17.

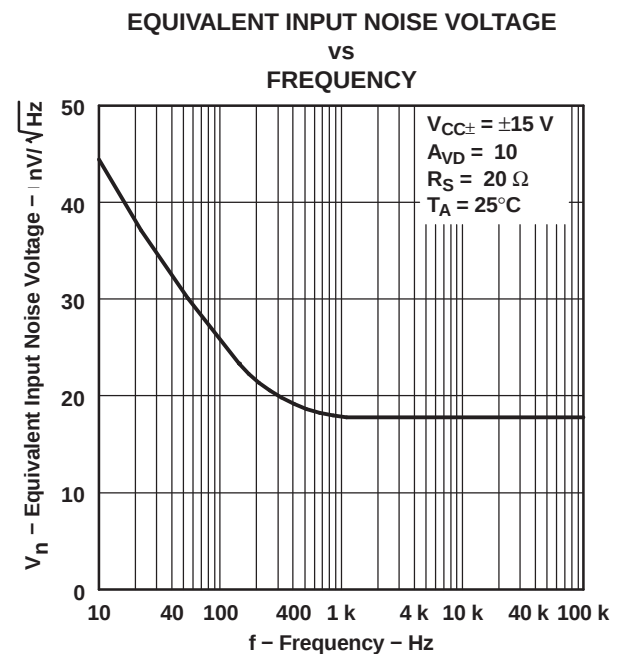


Figure 18.

TYPICAL CHARACTERISTICS (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

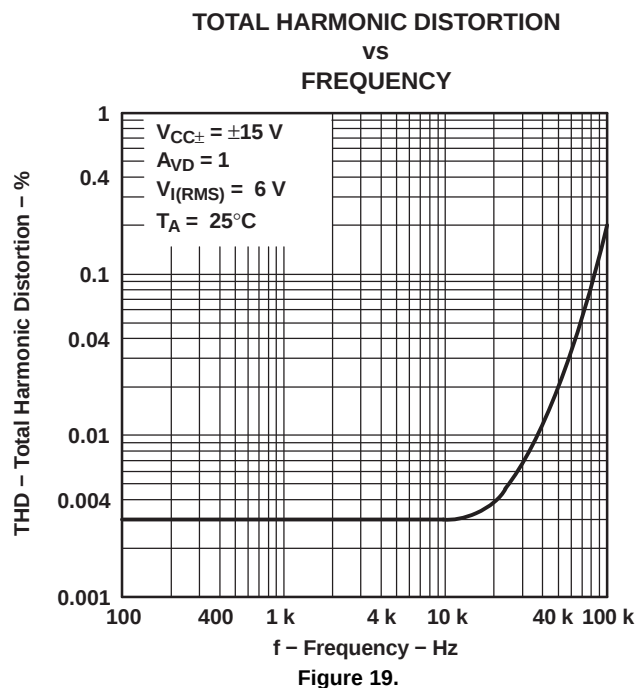


Figure 19.

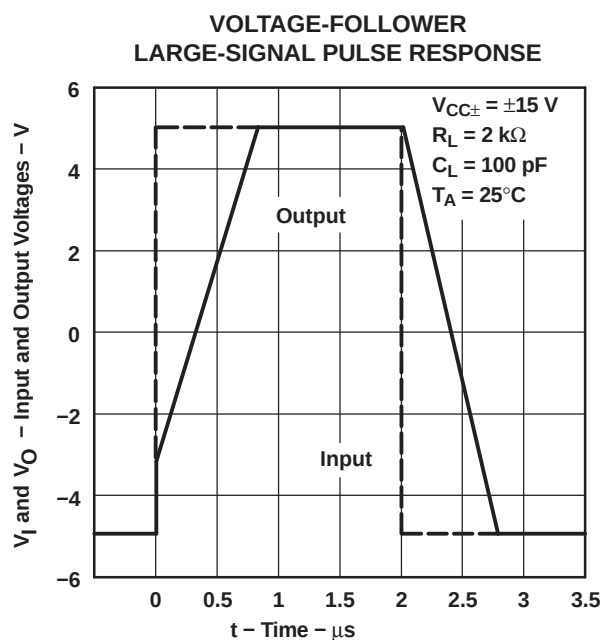


Figure 20.

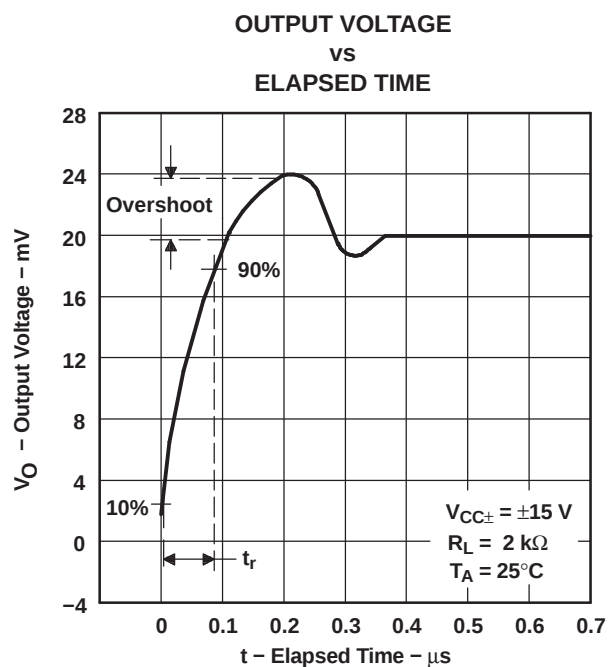
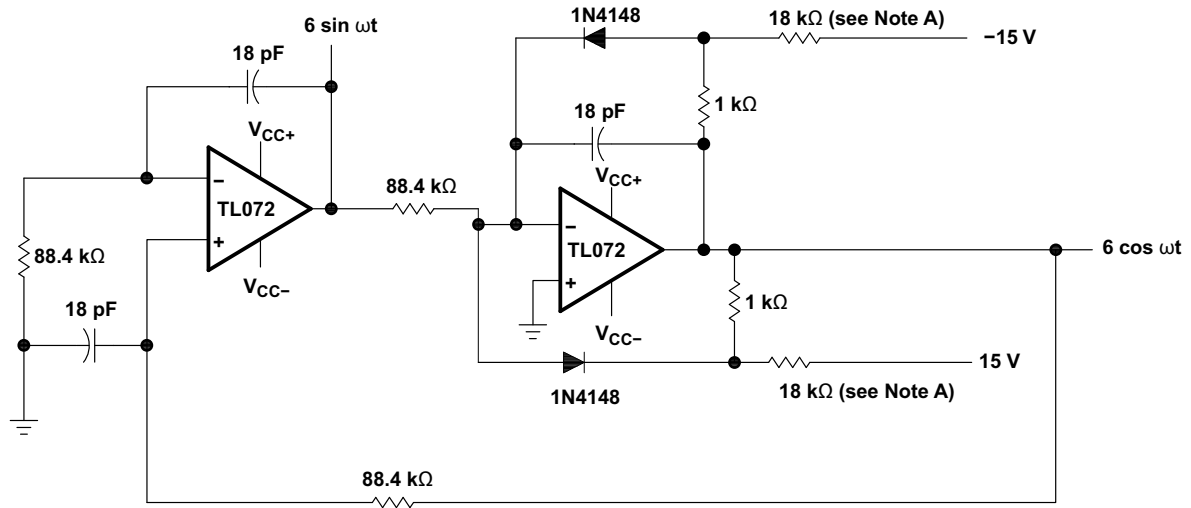


Figure 21.

APPLICATION INFORMATION



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 22. 100-kHz Quadrature Oscillator

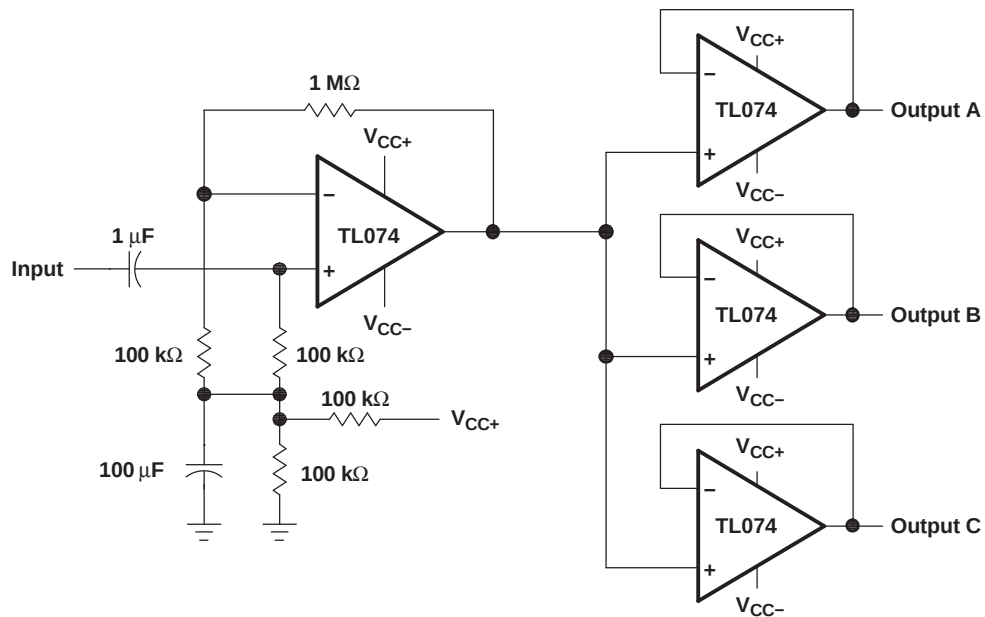


Figure 23. Audio-Distribution Amplifier

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL072QDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL072Q	Samples
TL074MDEP	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
TL074MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
TL074QDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL074Q	Samples
V62/11621-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL074Q	Samples
V62/11621-02XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
V62/11621-02XE-T	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TL074M	Samples
V62/12604-01XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL072Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TL072-EP, TL074-EP :

- Catalog: [TL072](#), [TL074](#)
- Military: [TL072M](#), [TL074M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL072QDREP	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
TL074MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL074QDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL072QDREP	SOIC	D	8	2500	340.5	338.1	20.6
TL074MDREP	SOIC	D	14	2500	333.2	345.9	28.6
TL074QDREP	SOIC	D	14	2500	333.2	345.9	28.6

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

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